

Bill of Materials

TI DESIGNS

TIEPD0020 - AM437x Discrete Power

Item	Count	RefDes	Value	Description	Size	Part Number	MFR
1	2	C1, C4	47uF	Capacitor, ceramic, 6.3-V, X5R, 20%	805	Std	Std
2	4	C2, C7, C9, C11	10uF	Capacitor, ceramic, 6.3-V, X5R, 20%	603	Std	Std
3	1	C3	22uF	Capacitor, ceramic, 6.3-V, X5R, 20%	805	GRM21BR60J226ME39L	Murata
4	1	C5	4.7uF	Capacitor, ceramic, 6.3-V, X5R, 20%	603	GRM188R60J475ME84	Murata
5	1	C6	1uF	Capacitor, ceramic, 10-V, X5R, 20%	603	GRM188R61A105KA61	Murata
6	2	C8, C10	2.2uF	Capacitor, ceramic, 6.3-V, X5R, 20%	603	GRM188R61A225KE34	Murata
7	1	R1	57.5kΩ	Resistor, chip, 1/16W, 1%	603	Std	Std
8	1	R2	39.2kΩ	Resistor, chip, 1/16W, 1%	603	Std	Std
9	1	R3	178kΩ	Resistor, chip, 1/16W, 1%	603	Std	Std
10	1	R4	47.5kΩ	Resistor, chip, 1/16W, 1%	603	Std	Std
11	1	R5	536kΩ	Resistor, chip, 1/16W, 1%	603	Std	Std
12	1	R6	120kΩ	Resistor, chip, 1/16W, 1%	603	Std	Std
13	1	R7	6.04kΩ	Resistor, chip, 1/16W, 1%	603	Std	Std
14	1	R8	1.54kΩ	Resistor, chip, 1/16W, 1%	603	Std	Std
15	1	L1	1uH	Inductor, power, 2.2-A, ±20%	3.05mmx3.05mm	XFL3012-102MEB	Coilcraft
16	1	L2	2.2uH	Inductor, LQH44PN_SERIES, ± 20%	1515	LQH44PN2R2MP0	Murata
17	1	U1	TLV62565	IC, 1.5A High Efficiency Step Down Converter	SOT-23-5	TLV62565DBV	TI
18	1	U2	TLV70215	IC, 300mA low drop regulator	SOT-23-5	TLV70215DBV	TI
19	1	U3	TLV70218	IC, 300mA low drop regulator	SOT-23-5	TLV70218DBV	TI
20	1	U4	TLV803M	IC, 3pin voltage supervisors	SOT-23-3	TLV803ZDBZ	TI
21	1	U5	TLV62080	IC, 1.2-A sync. step-down converter	SON-8	TLV62080DSG	TI
22	1	N/A	N/A	Processor	N/A	AM437x	TI

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